

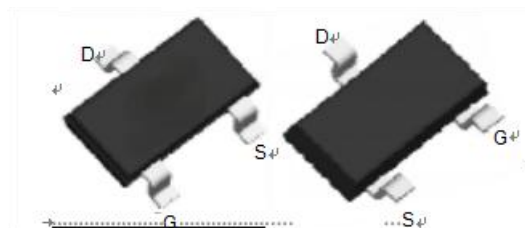


AO3400A

30V N-Channel MOSFET

General Description

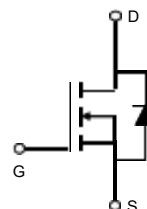
The AO3400A combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. This device is suitable for use as a load switch or in PWM applications.



Product Summary

V_{DS}	30V
I_b (at $V_{GS}=10V$)	5.7A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	< 26.5m Ω
$R_{DS(ON)}$ (at $V_{GS} = 4.5V$)	< 32m Ω
$R_{DS(ON)}$ (at $V_{GS} = 2.5V$)	< 48m Ω

SOT23
Top View Bottom View



Absolute Maximum Ratings $T_A=25^{\circ}C$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current	I_b	5.7	A
$T_A=25^{\circ}C$		4.7	
$T_A=70^{\circ}C$			
Pulsed Drain Current ^C	I_{DM}	30	
Power Dissipation ^B	P_D	1.4	W
$T_A=25^{\circ}C$		0.9	
$T_A=70^{\circ}C$			
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^{\circ}C$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	70	90	$^{\circ}C/W$
$t \leq 10s$				
Maximum Junction-to-Ambient ^{A D}		100	125	$^{\circ}C/W$
Steady-State				
Maximum Junction-to-Lead	$R_{\theta JL}$	63	80	$^{\circ}C/W$
Steady-State				

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =30V, V _{GS} =0V T _J =55°C			1 5	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} = ±12V			100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} I _D =250μA	0.65	1.05	1.45	V
I _{D(ON)}	On state drain current	V _{GS} =4.5V, V _{DS} =5V	30			A
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =5.7A T _J =125°C		18 28	26.5 38	mΩ
		V _{GS} =4.5V, I _D =5A		19	32	mΩ
		V _{GS} =2.5V, I _D =3A		24	48	mΩ
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =5.7A		33		S
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V		0.7	1	V
I _S	Maximum Body-Diode Continuous Current				2	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =15V, f=1MHz		630		pF
C _{oss}	Output Capacitance			75		pF
C _{rss}	Reverse Transfer Capacitance			50		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz	1.5	3	4.5	Ω
SWITCHING PARAMETERS						
Q _g	Total Gate Charge	V _{GS} =4.5V, V _{DS} =15V, I _D =5.7A		6	7	nC
Q _{gs}	Gate Source Charge			1.3		nC
Q _{gd}	Gate Drain Charge			1.8		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =15V, R _L =2.6Ω, R _{GEN} =3Ω		3		ns
t _r	Turn-On Rise Time			2.5		ns
t _{D(off)}	Turn-Off DelayTime			25		ns
t _f	Turn-Off Fall Time			4		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =5.7A, dI/dt=100A/μs		8.5		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =5.7A, dI/dt=100A/μs		2.6		nC

A. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_A =25 ° C. The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on T_{J(MAX)}=150 ° C, using ≤ 10s junction-to-ambient thermal resistance.

C. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150 ° C. Ratings are based on low frequency and duty cycles to keep initial T_J=25 ° C.

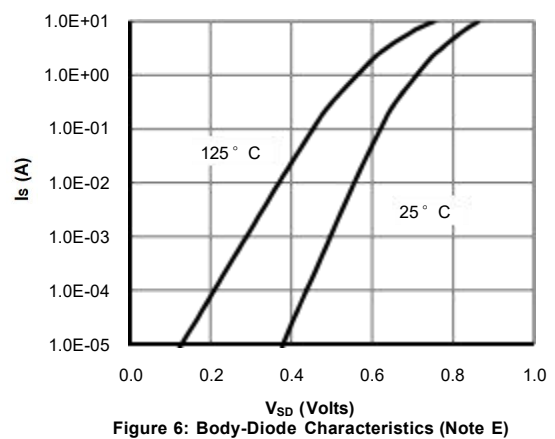
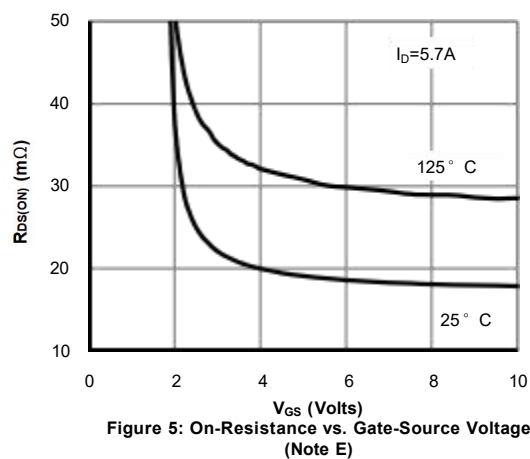
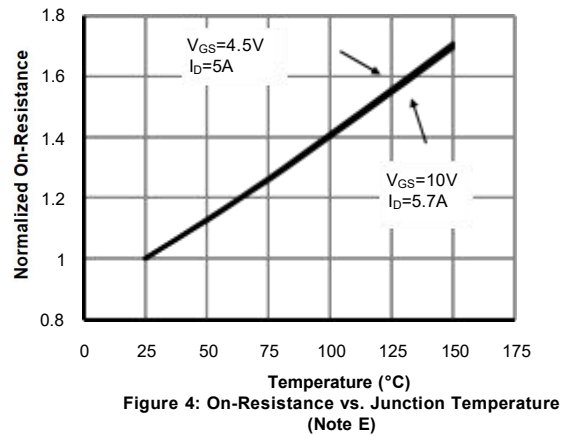
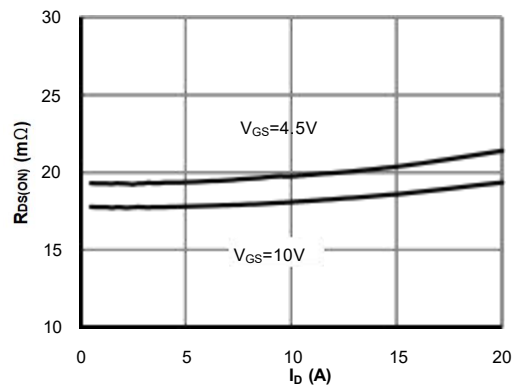
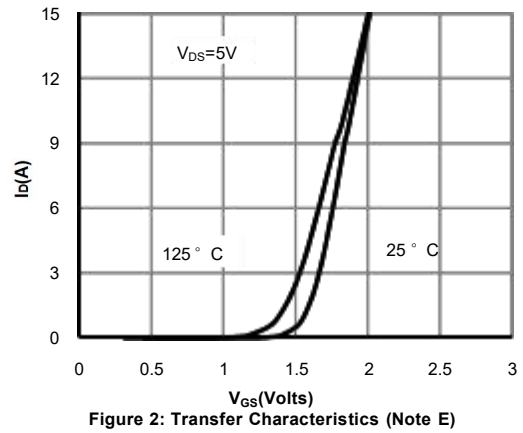
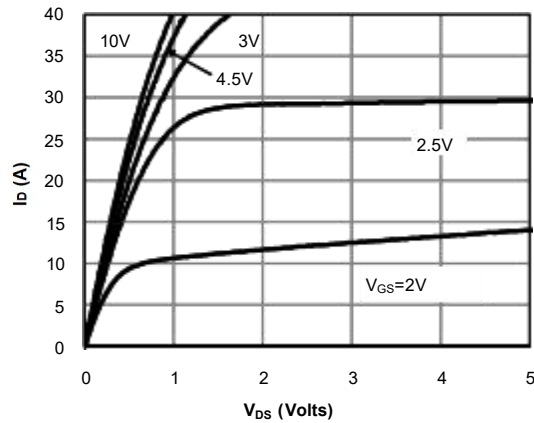
D. The R_{θJA} is the sum of the thermal impedance from junction to lead R_{θJL} and lead to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, assuming a maximum junction temperature of T_{J(MAX)}=150 ° C. The SOA curve provides a single pulse rating.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

AO3400A



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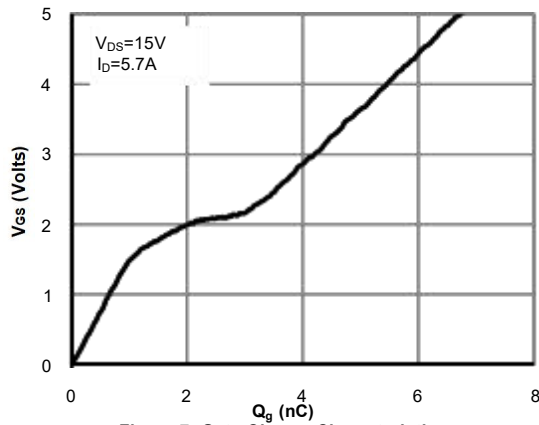


Figure 7: Gate-Charge Characteristics

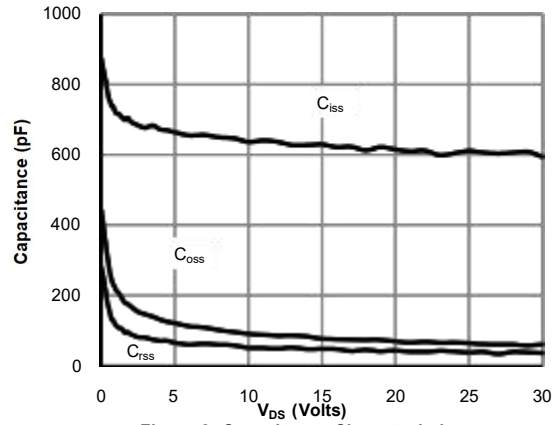


Figure 8: Capacitance Characteristics

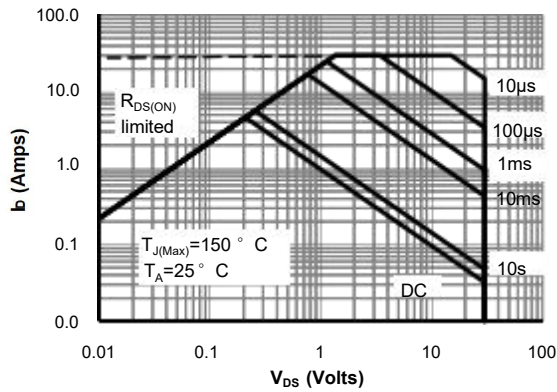


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

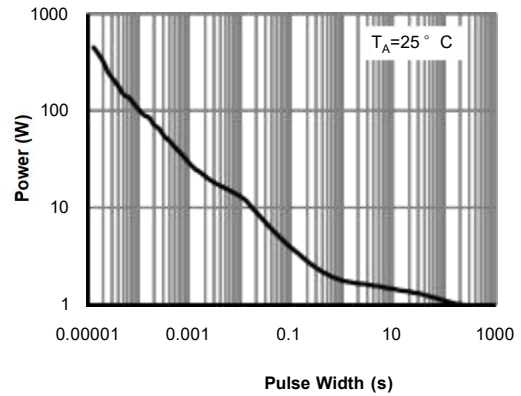


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

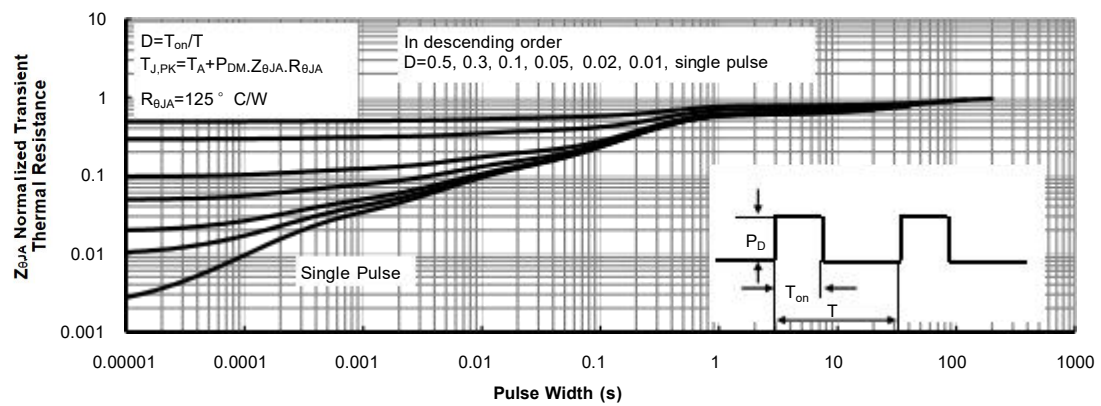
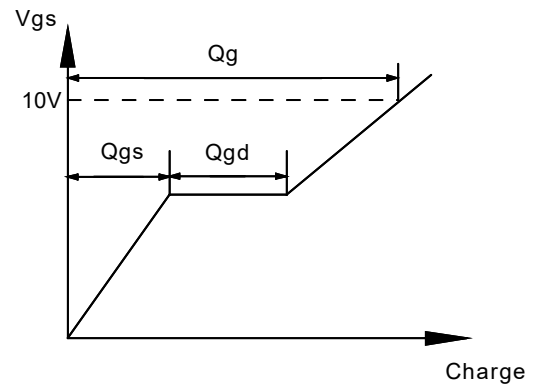
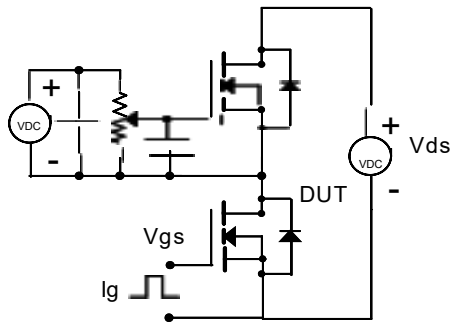
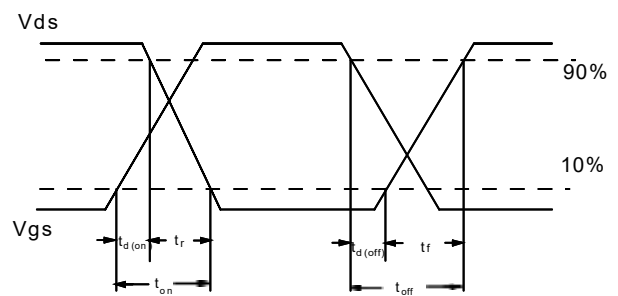
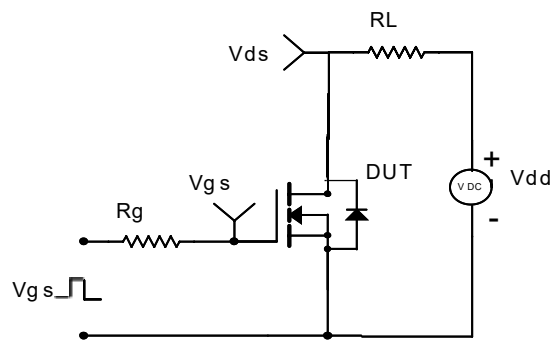


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

